



TSMC-00-240

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April 17, 2001

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Commissioner of Patents and Trademarks
Washington, D.C. 20231

Fr: George O. Saile, Reg. No. 19,572
20 McIntosh Drive
Poughkeepsie, N.Y. 12603

Subject:

Serial No. 09/769,812 01/26/01

Li-Te Lin, Li-Chih Chao,
Chia-Shiung Tsai

AN ORGANIC LOW K DIELECTRIC ETCH
WITH NH₃ CHEMISTRY

Grp. Art Unit: 1743 1746

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INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation
In An Application.

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The following Patents and/or Publications are submitted to comply with the duty of disclosure under CFR 1.97-1.99 and 37 CFR 1.56. Copies of each document is included herewith.

U.S. Patent 6,071,815 to Kleinhenz et al., "Method of Patterning Sidewalls of a Trench in Integrated Circuit Manufacturing", discloses a silicon oxide layer etch that uses HF and ammonia in combination with other gases.



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ASSOCIATE POWER OF ATTORNEY

I hereby appoint William Stoffel, registration number 39,390, as my associate attorney in this case. His telephone number is (215) 564-2258.

Please continue to direct all correspondence in this case to the undersigned attorney.

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Respectfully submitted,

Stephen B. Ackerman,

Principal attorney of record

U.S. Patent 5,897,377 to Suzuki, "Semiconductor Device Manufacturing Method with Use of Gas Including Acyl-Group-Containing Compound", discloses a surface treatment etch.

U.S. Patent 5,972,235 to Brigham et al., "Plasma Etching Using Polycarbonate Mask and Low Pressure-High Density Plasma", discloses a low-k etch.

U.S. Patent 6,063,712 to Gilton et al., "Oxide Etch and Method of Etching", teaches an oxide etch using ammonia a fluorine containing compound and a boron containing compound.

Sincerely,



Stephen B. Ackerman,
Reg. No. 37761